intel®

2916/2917
HMOS COMBINED SINGLE CHIP PCM CODEC AND FILTER

- 2916 μ-Law, 2.048 MHz Master Clock
- 2917 A-Law, 2.048 MHz Master Clock
- New 16-Pin Package for Higher Linecard Density
- AT&T D3/D4 and CCITT Compatible
- Variable Timing Mode for Flexible Digital Interface: Supports Data Rates from 64 KB to 2.048 MB
- Fully Differential Internal Architecture Enhances Noise Immunity

- Fixed Timing Mode for Standard 32-Channel Systems: 2.048 MHz Master Clock
- Low Power HMOS-E Technology
  — 5 mW Typical Power Down
  — 140 mW Typical Operating
- On Chip Auto Zero, Sample and Hold, and Precision Voltage References
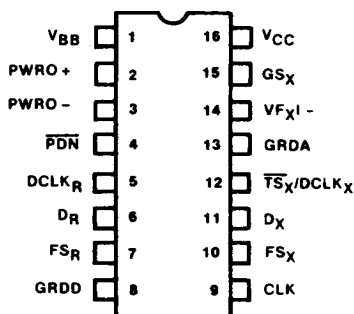- Compatible with Direct Mode Intel 2910A, 2911A, and 2912A Designs

The Intel 2916 and 2917 are limited feature versions of Intel's 2913 and 2914 combination codec/filter chips. They are fully integrated PCM codecs with transmit/receive filters fabricated in a highly reliable and proven N-channel HMOS silicon gate technology (HMOS-E). These devices provide the functions that were formerly provided by two complex chips (2910A or 2911A and 2912A). Besides the higher level of integration, the performance of the 2916 and 2917 is superior to that of the separate devices.

The primary applications for the 2916 and 2917 are in telephone systems:

- Switching—Digital PBX's and Central Office Switching Systems
- Subscriber Instruments—Digital Handsets and Office Workstations

Other possible applications can be found where the wide dynamic range (78 dB) and minimum conversion time (125 μs) are required for analog to digital interface functions:

- High Speed Modems
- Voice Store and Forward
- Secure Communications
- Digital Echo Cancellation

5

Pin			Pin	
V_{BB}		1	16	V_{CC}
PWRO+		2	15	GS_X
PWRO−		3	14	VF_XI-
$\overline{PDN}$		4	13	GRDA
$DCLK_R$		5	12	$\overline{TS_X}/DCLK_X$
D_R		6	11	D_X
FS_R		7	10	FS_X
GRDD		8	9	CLK

270156–1

Figure 1. Pin Configuration
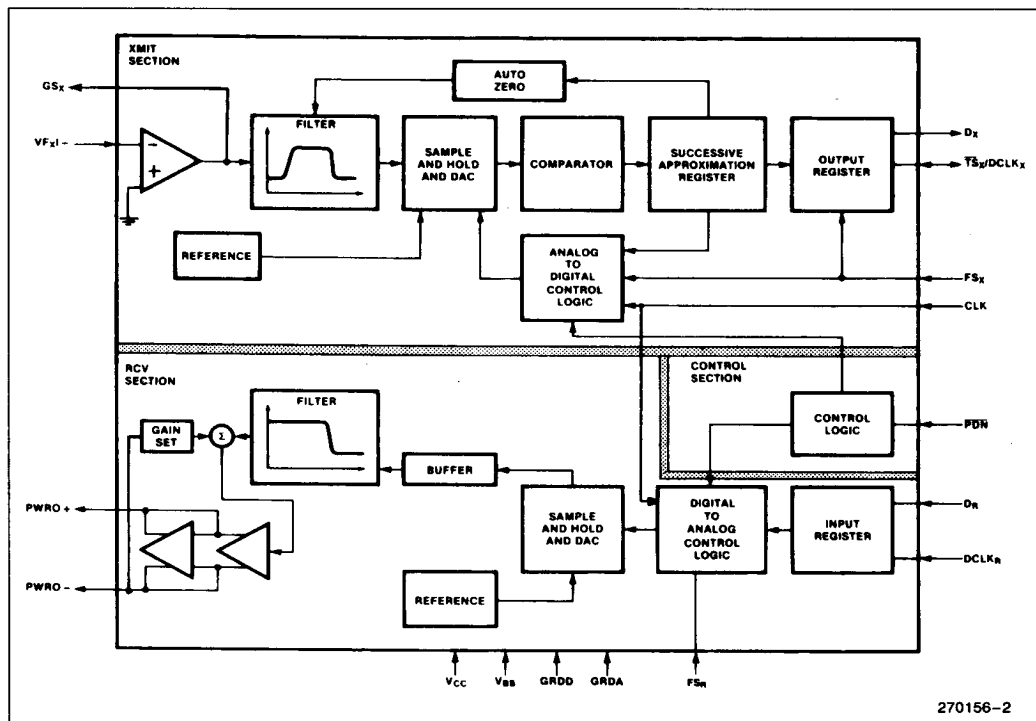
Figure 2. Block Diagram

Table 1. Pin Names

Name	Description	Name	Description
V_{BB}	Power ($-5V$)	GS_X	Transmit Gain Control
PWRO+, PWRO−	Power Amplifier Outputs	VF_XI-	Analog Input
$\overline{PDN}$	Power Down Select	GRDA	Analog Ground
$DCLK_R$	Receive Variable Data Clock	$\overline{TS}_X$	Timeslot Strobe/Buffer Enable
D_R	Receive PCM Input	$DCLK_X$	Transmit Variable Data Clock
FS_R	Receive Frame Synchronization Clock	D_X	Transmit PCM Output
		FS_X	Transmit Frame Synchronization Clock
GRDD	Digital Ground		
V_{CC}	Power ($+5V$)	CLK	Master Clock

Table 2. Pin Description

Symbol	Function
V_{BB}	Most negative supply, input voltage is -5 volts $\pm 5\%$.
PWRO+	Non-inverting output of power amplifier. Can drive transformer hybrids or high impedance loads directly in either a differential or single ended configuration.
PWRO−	Inverting output of power amplifier. Functionally identical and complementary to PWRO+.
$\overline{PDN}$	Power down select. When $\overline{PDN}$ is TTL high, the device is active. When low, the device is powered down.
$DCLK_R$	Selects the fixed or variable data rate mode. When $DCLK_R$ is connected to V_{BB}, the fixed data rate mode is selected. When $DCLK_R$ is not connected to V_{BB}, the device operates in the variable data rate mode. In this mode $DCLK_R$ becomes the receive data clock which operates at TTL levels from 64 Kb to 2.048 Mb data rates.
D_R	Receive PCM input. PCM data is clocked in on this lead on eight consecutive negative transitions of the receive data clock; CLK in the fixed data rate mode and $DCLK_R$ in variable data rate mode.
FS_R	8 KHz frame synchronization clock input/timeslot enable, receive channel. In variable data rate mode this signal must remain high for the entire length of the timeslot. The receive channel enters the standby state whenever FS_R is TTL low for 300 milliseconds.
GRDD	Digital ground for all internal logic circuits. Not internally tied to GRDA.
CLK	Master and data clock for the fixed data rate mode; master clock only in variable data rate mode.
FS_X	8 KHz frame synchronization clock input/timeslot enable, transmit channel. Operates independently but in an analogous manner to FS_R. The transmit channel enters the standby state whenever FS_X is TTL low for 300 milliseconds.
D_X	Transmit PCM output. PCM data is clocked out on this lead on eight consecutive positive transitions of the transmit data clock; CLK in fixed data rate mode and $DCLK_X$ in variable data rate mode.
$\overline{TS}_X/DCLK_X$	Transmit channel timeslot strobe (output) or data clock (input) for the transmit channel. In fixed data rate mode, this pin is an open drain output designed to be used as an enable signal for a three-state buffer. In variable data rate mode, this pin becomes the transmit data clock which operates at TTL levels from 64 Kb to 2.048 Mb data rates.
GRDA	Analog ground return for all internal voice circuits. Not internally connected to GRDD.
$VF_X I-$	Inverting analog input to uncommitted transmit operational amplifier.
GS_X	Output terminal of on-chip transmit channel input op amp. Internally, this is the voice signal input to the transmit filter.
V_{CC}	Most positive supply; input voltage is $+5$ volts $\pm 5\%$.

5

FUNCTIONAL DESCRIPTION

The 2916 and 2917 provide the analog-to-digital and the digital-to-analog conversions and the transmit and receive filtering necessary to interface a full duplex (4 wires) voice telephone circuit with the PCM highways of a time division multiplexed (TDM) system. They are intended to be used at the analog termination of a PCM line.

The following major functions are provided:

- Bandpass filtering of the analog signals prior to encoding and after decoding
- Encoding and decoding of voice and call progress information
- Encoding and decoding of the signaling and supervision information

GENERAL OPERATION

System Reliability Features

The combochip can be powered up by pulsing FS_X and/or FS_R while a TTL high voltage is applied to $\overline{PDN}$, provided that all clocks and supplies are connected. The 2916 and 2917 have internal resets on power up (or when V_{BB} or V_{CC} are re-applied) in order to ensure validity of the digital outputs and thereby maintain integrity of the PCM highway.

On the transmit channel, digital outputs D_X and $\overline{TS}_X$ are held in a high impedance state for approximately four frames (500 μs) after power up or application of V_{BB} or V_{CC}. After this delay, D_X and $\overline{TS}_X$ will be functional and will occur in the proper timeslot. The analog circuits on the transmit side require approximately 60 milliseconds to reach their equilibrium value due to the autozero circuit settling time.

To enhance system reliability, $\overline{TS}_X$ and D_X will be placed in a high impedance state approximately 30 μs after an interruption of CLK.

Power Down and Standby Modes

To minimize power consumption, two power down modes are provided in which most 2916/2917 functions are disabled. Only the power down, clock, and frame sync buffers, which are required to power up the device, are enabled in these modes. As shown in Table 3, the digital outputs on the appropriate channels are placed in a high impedance state until the device returns to the active mode.

The Power Down mode utilizes an external control signal to the $\overline{PDN}$ pin. In this mode, power consumption is reduced to an average of 5 mW. The device is active when the signal is high and inactive when it is low. In the absence of any signal, the $\overline{PDN}$ pin floats to TTL high allowing the device to remain active continuously.

The Standby mode leaves the user an option of powering either channel down separately or powering the entire device down by selectively removing FS_X and/or FS_R. With both channels in the standby state, power consumption is reduced to an average of 12 mW. If transmit only operation is desired, FS_X should be applied to the device while FS_R is held low. Similarly, if receive only operation is desired, FS_R should be applied while FS_X is held low.

Fixed Data Rate Mode

Fixed data rate timing, which is 2910A and 2911A compatible, is selected by connecting $DCLK_R$ to V_{BB}. It employs master clock CLK, frame synchronization clocks FS_X and FS_R, and output $\overline{TS}_X$.

Table 3. Power-Down Methods

Device Status	Power-Down Method	Typical Power Consumption	Digital Output Status
Power Down Mode	$\overline{PDN}$ = TTL Low	5 mW	$\overline{TS}_X$ and D_X are placed in a high impedance state within 10 μs.
Standby Mode	FS_X and FS_R are TTL Low	12 mW	$\overline{TS}_X$ and D_X are placed in a high impedance state within 300 milliseconds.
Only Transmit is on Standby	FS_X is TTL Low	70 mW	$\overline{TS}_X$ and D_X are placed in a high impedance state within 300 milliseconds.
Only Receive is on Standby	FS_R is TTL Low	110 mW	

CLK serves as the master clock to operate the codec and filter sections and as the bit clock to clock the data in and out from the PCM highway. FS_X and FS_R are 8 KHz inputs which set the sampling frequency. $\overline{TS}_X$ is a timeslot strobe/buffer enable output which gates the PCM word onto the PCM highway when an external buffer is used to drive the line.

Data is transmitted on the highway at D_X on the first eight positive transitions of CLK following the rising edge of FS_X. Similarly, on the receive side, data is received on the first eight falling edges of CLK. The frequency of CLK must be 2.048 MHz. No other frequency of operation is allowed in the fixed data rate mode.

Variable Data Rate Mode

Variable data rate timing is selected by connecting $DCLK_R$ to the bit clock for the receive PCM highway rather than to V_{BB}. It employs master clock CLK, bit clocks $DCLK_R$ and $DCLK_X$, and frame synchronization clocks FS_R and FS_X.

Variable data rate timing allows for a flexible data frequency. It provides the ability to vary the frequency of the bit clocks, from 64 KHz to 2.048 MHz. The master clock is still restricted to 2.048 MHz.

In this mode, $DCLK_R$ and $DCLK_X$ become the data clocks for the receive and transmit PCM highways. While FS_X is high, PCM data from D_X is transmitted onto the highway on the next eight consecutive positive transitions of $DCLK_X$. Similarly, while FS_R is high, each PCM bit from the highway is received by D_R on the next eight consecutive negative transitions of $DCLK_R$.

On the transmit side, the PCM word will be repeated in all remaining timeslots in the 125 μs frame as long as $DCLK_X$ is pulsed and FS_X is held high. This feature allows the PCM word to be transmitted to the PCM highway more than once per frame, if desired, and is only available in the variable data rate mode.

Precision Voltage References

No external components are required with the combochip to provide the voltage reference function. Voltage references are generated on-chip and are calibrated during the manufacturing process. The technique uses a difference in sub-surface charge density between two suitably implanted MOS devices to derive a temperature and bias stable reference voltage. These references determine the gain and dynamic range characteristics of the device.

Separate references are supplied to the transmit and receive sections and each is trimmed independently during the manufacturing process. The reference value is then further trimmed in the gain setting op-amps to a final precision value. With this method the combochip can achieve the extremely accurate Digital Milliwatt Responses specified in the transmission parameters, providing the user a significant margin for error in other board components.

TRANSMIT OPERATION

Transmit Filter

The input section provides gain adjustment in the passband by means of an on-chip operational amplifier. This operational amplifier has a commoon mode range of ±2.17 volts, a maximum DC offset of 25 mV, a minimum open loop voltage gain of 5000, and a unity gain bandwidth of typically 1 MHz. Gain of up to 20 dB can be set without degrading the performance of the filter. The load impedance to ground (GRDA) at the amplifier output (GS_X) must be greater than 10 kilohms in parallel with less than 50 pF. The input signal on lead $VF_X I-$ can be either AC or DC coupled. The input op amp can only be used in the inverting mode as shown in Figure 3.

A low pass anti-aliasing section is included on-chip. This section typically provides 35 dB attenuation at the sampling frequency. No external components are required to provide the necessary anti-aliasing function for the switched capacitor section of the transmit filter.
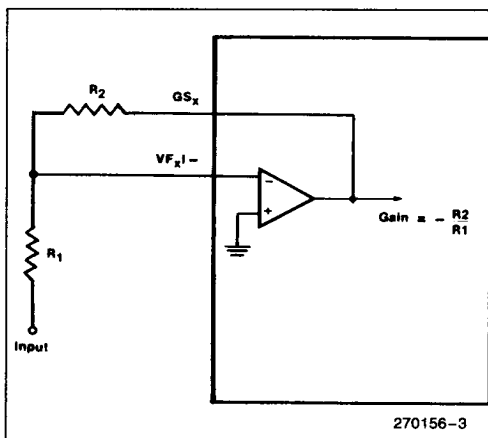

Figure 3. Transmit Filter Gain Adjustment

The passband section provides flatness and stop-band attenuation which fulfills the AT&T D3/D4 channel bank transmission specification and CCITT recommendation G.714. The 2916 and 2917 specifications meet or exceed digital class 5 central office switching systems requirements. The transmit filter transfer characteristics and specifications will be within the limits shown in Figure 4.

A high pass section configuration was chosen to reject low frequency noise from 50 and 60 Hz power lines, 17 Hz European electric railroads, ringing frequencies and their harmonics, and other low frequency noise. Even though there is high rejection at these frequencies, the sharpness of the band edge gives low attenuation at 200 Hz. This feature allows the use of low-cost transformer hybrids without external components.

Encoding

The encoder internally samples the output of the transmit filter and holds each sample on an internal sample and hold capacitor. The encoder then performs an analog to digital conversion on a switched capacitor array. Digital data representing the sample is transmitted on the first eight data clock bits of the next frame.

An on-chip autozero circuit corrects for DC-offset on the input signal to the encoder. This autozero circuit uses the sign bit averaging technique; the sign bit from the encoder output is long term averaged and subtracted from the input to the encoder. In this way, all DC offset is removed from the encoder input waveform.

RECEIVE OPERATION

Decoding

The PCM word at the D_R lead is serially fetched on the first eight data clock bits of the frame. A D/A conversion is performed on the digital word and the corresponding analog sample is held on an internal sample and hold capacitor. This sample is then transferred to the receive filter.

Receive Filter

The receive filter provides passband flatness and stopband rejection which fulfills both the AT&T D3/D4 specification and CCITT recommendation G.714. The filter contains the required compensation for the (sin x)/x response of such decoders. The receive filter characteristics and specifications will be within the limits shown in Figure 5.

Receive Output Power Amplifiers

A balanced output amplifier is provided in order to allow maximum flexibility in output configuration. Either of the two outputs can be used single ended (referenced to GRDA) to drive single ended loads. Alternatively, the differential output will drive a bridged load directly. The output stage is capable of driving loads as low as 300 ohms single ended or 600 ohms differentially.

Transmission levels are specified relative to the receive channel output under digital milliwatt conditions, that is, when the digital input at D_R is the eight-code sequence specified in CCITT recommendation G.711.

Table 4. Zero Transmission Level Points

Symbol	Parameter	Value	Units	Test Conditions
$OTLP1_X$	Zero Transmission Level Point Transmit Channel (0dBm0) μ-law	+ 2.76 + 1.00	dBm dBm	Referenced to 600Ω Referenced to 900Ω
$OTLP2_X$	Zero Transmission Level Point Transmit Channel (0dBm0) A-law	+ 2.79 + 1.03	dBm dBm	Referenced to 600Ω Referenced to 900Ω
$OTLP1_R$	Zero Transmission Level Point Receive Channel (0dBm0) μ-law	+ 5.76 + 4.00	dBm dBm	Referenced to 600Ω Referenced to 900Ω
$OTLP2_R$	Zero Transmission Level Point Receive Channel (0dBm0) A-law	+ 5.79 + 4.03	dBm dBm	Referenced to 600Ω Referenced to 900Ω

ABSOLUTE MAXIMUM RATINGS

Temperature Under Bias . . . . $-10°C$ to $+80°C$

Storage Temperature . . . . $-65°C$ to $+150°C$

V_{CC} and GRDD with Respect
to V_{BB} . . . . $-0.3V$ to $+15V$

All Input and Output Voltages
with Respect to V_{BB} . . . . $-0.3V$ to $+15V$

Power Dissipation 1.35W

> NOTICE: This is a production data sheet. The specifications are subject to change without notice.
>
> *WARNING: Stressing the device beyond the "Absolute Maximum Ratings" may cause permanent damage. These are stress ratings only. Operation beyond the "Operating Conditions" is not recommended and extended exposure beyond the "Operating Conditions" may affect device reliability.

D.C. CHARACTERISTICS

$(T_A = 0°C$ to $70°C$, $V_{CC} = +5V \pm 5\%$, $V_{BB} = -5V \pm 5\%$, GRDA $= 0V$, GRDD $= 0V$, unless otherwise specified)

Typical values are for $T_A = 25°C$ and nominal power supply values.

DIGITAL INTERFACE

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
I_{IL}	Low Level Input Current			10	μA	GRDD $\leq V_{IN} \leq V_{IL}$ (Note 1)
I_{IH}	High Level Input Current			10	μA	$V_{IH} \leq V_{IN} \leq V_{CC}$
V_{IL}	Input Low Voltage			0.8	V	
V_{IH}	Input High Voltage	2.0			V	
V_{OL}	Output Low Voltage			0.4	V	$I_{OL} = 3.2$ mA at D_X, $\overline{TS}_X$
V_{OH}	Output High Voltage	2.4			V	$I_{OH} = 9.6$ mA at D_X
C_{OX}	Digital Output Capacitance[2]		5		pF	
C_{IN}	Digital Input Capacitance		5	10	pF	

5

POWER DISSIPATION

All measurements made at $f_{DCLK} = 2.048$ MHz, outputs unloaded.

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
I_{CC1}	V_{CC} Operating Current[4]		14	19	mA	
I_{BB1}	V_{BB} Operating Current		-18	-24	mA	
I_{CC0}	V_{CC} Power Down Current		0.5	1.0	mA	$\overline{PDN} \leq V_{IL}$; after 10 μs
I_{BB0}	V_{BB} Power Down Current		-0.5	-1.0	mA	$\overline{PDN} \leq V_{IL}$; after 10 μs
I_{CCS}	V_{CC} Standby Current		1.2	2.4	mA	$FS_X, FS_R \leq V_{IL}$; after 300 ms
I_{BBS}	V_{BB} Standby Current		-1.2	-2.4	mA	$FS_X, FS_R \leq V_{IL}$; after 300 ms
P_{D1}	Operating Power Dissipation[3]		140	200	mW	
P_{D0}	Power Down Dissipation[3]		5	10	mW	$\overline{PDN} \leq V_{IL}$; after 10 μs
P_{ST}	Standby Power Dissipation[3]		12	25	mW	$FS_X, FS_R \leq V_{IL}$

NOTES:
1. V_{IN} is the voltage on any digital pin.
2. Timing parameters are guaranteed based on a 100 pF load capacitance. Up to eight digital outputs may be connected to a common PCM highway without buffering, assuming a board capacitance of 60 pF.
3. With nominal power supply values.
4. V_{CC} applied last or simultaneously with V_{BB}.

ANALOG INTERFACE, TRANSMIT CHANNEL INPUT STAGE

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
I_{BX1}	Input Leakage Current, VF_XI-			100	nA	$-2.17V \leq V_{IN} \leq 2.17V$
R_{IXI}	Input Resistance, VF_XI-	10			$M\Omega$	
V_{OSXI}	Input Offset Voltage, VF_XI-			25	mV	
A_{VOL}	DC Open Loop Voltage Gain, GS_X	5000				
f_C	Open Loop Unity Gain Bandwidth, GS_X		1		MHz	
C_{LXI}	Load Capacitance, GS_X			50	pF	
R_{LXI}	Minimum Load Resistance, GS_X	10			$K\Omega$	

ANALOG INTERFACE, RECEIVE CHANNEL DRIVER AMPLIFIER STATE

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
R_{ORA}	Output Resistance, PWRO+, PWRO−		1		Ω	
V_{OSRA}	Single-Ended Output DC Offset, PWRO+, PWRO−		75		mV	Relative to GRDA
C_{LRA}	Load Capacitance, PWRO+, PWRO−			100	pF	

A.C. CHARACTERISTICS—TRANSMISSION PARAMETERS

Unless otherwise noted, the analog input is a 0 dBm0, 1020 Hz sine wave.[1] Input amplifier is set for unity gain, inverting. The digital input is a PCM bit stream generated by passing a 0 dBm0, 1020 Hz sine wave through an ideal encoder. Receive output is measured single ended. All output levels are (sin x)/x corrected. Typical values are for T_A = 25°C and nominal power supply values. (T_A = 0°C to +70°C; V_{CC} = +5V; V_{BB} = −5V ±5%; GRDA = 0V; GRDD = 0V; unless otherwise specified).

GAIN AND DYNAMIC RANGE

Symbol	Parameter	Min	Typ	Max	Units	Test Conditions
EmW	Encoder Milliwatt Response (Transmit Gain Tolerance)	−0.18	±0.04	+0.18	dBm0	Signal Input of 1.064 Vrms μ-law Signal Input of 1.068 Vrms A-law T_A = 25°C, V_{BB} = −5V, V_{CC} = +5V
EmW_{TS}	EmW Variation with Temperature and Supplies	−0.07	±0.02	+0.07	dB	±5% Supplies, 0 to 70°C Relative to Nominal Conditions
DmW	Digital Milliwatt Response (Receive Gain Tolerance)	−0.18	±0.04	+0.18	dBm0	Measure Relative to $0TLP_R$. Signal Input per CCITT Recommendation G.711. Output Signal of 1000 Hz. R_L = ∞ T_A = 25°C; V_{BB} = −5V, V_{CC} = +5V.
DmW_{TS}	DmW Variation with Temperature and Supplies	−0.07	±0.02	+0.07	dB	±5% Supplies, 0 to 70°C

NOTE:
1. 0 dBm0 is defined as the zero reference point of the channel under test (0TLP). This corresponds to an analog signal input of 1.064 volts rms or an output of 1.503 volts rms (for μlaw).

GAIN TRACKING

Reference Level $= -10$ dBm0

Symbol	Parameter	2916		2917		Unit	Test Conditions
		Min	Max	Min	Max		
GT1$_X$	Transmit Gain Tracking Error Sinusoidal Input; μ-law		±0.25 ±0.5 ±1.2			dB dB dB	+3 to −40 dBm0 −40 to −50 dBm0 −50 to −55 dBm0
GT2$_X$	Transmit Gain Tracking Error Sinusoidal Input; A-law				±0.25 ±0.5 ±1.2	dB dB dB	+3 to −40 dBm0 −40 to −50 dBm0 −50 to −55 dBm0
GT1$_R$	Receive Gain Tracking Error Sinusoidal Input; μ-law		±0.25 ±0.5 ±1.2			dB dB dB	+3 to −40 dBm0 −40 to −50 dBm0 −50 to −55 dBm0 Measured at PWRO+, $R_L = 300\Omega$
GT2$_R$	Receive Gain Tracking Error Sinusoidal Input; A-law				±0.25 ±0.5 ±1.2	dB dB dB	+3 to −40 dBm0 −40 to −50 dBm0 −50 to −55 dBm0 Measured at PWRO+, $R_L = 300\Omega$

NOISE (All receive channel measurements are single ended)

Symbol	Parameter	2916			2917			Unit	Test Conditions
		Min	Typ	Max	Min	Typ	Max		
N$_{XC1}$	Transmit Noise, C-Message Weighted			15				dBrncO	Unity Gain
N$_{XP}$	Transmit Noise, Psophometrically Weighted						−75	dBm0p	Unity Gain
N$_{RC1}$	Receive Noise, C-Message Weighted: Quiet Code			11				dBrncO	$D_R = 11111111$
N$_{RC2}$	Receive Noise, C-Message Weighted: Sign Bit Toggle			12				dBrncO	Input to D_R is Zero Code with Sign Bit Toggle at 1 KHz Rate
N$_{RP}$	Receive Noise, Psophometrically Weighted						−79	dBm0p	D_R = Lowest Positive Decode Level
N$_{SF}$	Single Frequency Noise End to End Measurement			−50			−50	dBm0	CCITT G.712.4.2 Measure at PWRO+
PSRR$_1$	V$_{CC}$ Power Supply Rejection, Transmit Channel		−30			−30		dB	Idle Channel; 200 mV P-P Signal on Supply; 0 to 50 KHz, Measure at D$_X$
PSRR$_2$	V$_{BB}$ Power Supply Rejection, Transmit Channel		−30			−30		dB	Idle Channel; 200 mV P-P Signal on Supply; 0 to 50 KHz, Measure at D$_X$
PSRR$_3$	V$_{CC}$ Power Supply Rejection, Receive Channel		−25			−25		dB	Idle Channel; 200 mV P-P Signal on Supply; Measure Narrow Band at PWRO+, 0 to 50 KHz
PSRR$_4$	V$_{BB}$ Power Supply Rejection, Receive Channel		−25			−25		dB	Idle Channel; 200 mV P-P Signal on Supply; Measure Narrow Band at PWRO+, 0 to 50 KHz
CT$_{TR}$	Crosstalk, Transmit to Receive			−71			−71	dB	Input = 0 dBm0, Unity Gain, 1.02 KHz, D_R = Lowest Positive Decode Level, Measure at PWRO+
CT$_{RT}$	Crosstalk, Receive to Transmit			−71			−71	dB	D_R = 0 dBm0, 1.02 KHz, Measure at D$_X$

5

DISTORTION

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
SD1$_X$	Transmit Signal to Distortion, μ-Law Sinusoidal Input; CCITT G.714-Method 2 (2916)	36 30 25			dB dB dB	0 dBm0 to $-$30 dBm0 $-$30 dBm0 to $-$40 dBm0 $-$40 dBm0 to $-$45 dBm0
SD2$_X$	Transmit Signal to Distortion, A-Law Sinusoidal Input; CCITT G.714-Method 2 (2917)	36 30 25			dB dB dB	0 dBm0 to $-$30 dBm0 $-$30 dBm0 to $-$40 dBm0 $-$40 dBm0 to $-$45 dBm0
SD1$_R$	Receive Signal to Distortion, μ-Law Sinusoidal Input; CCITT G.714-Method 2 (2916)	36 30 25			dB dB dB	0 dBm0 to $-$30 dBm0 $-$30 dBm0 to $-$40 dBm0 $-$40 dBm0 to $-$45 dBm0
SD2$_R$	Receive Signal to Distortion, A-Law Sinusoidal Input; CCITT G.714-Method 2 (2917)	36 30 25			dB dB dB	0 dBm0 to $-$30 dBm0 $-$30 dBm0 to $-$40 dBm0 $-$40 dBm0 to $-$45 dBm0
DP$_X$	Transmit Single Frequency Distortion Products (2916)			$-$46	dBm0	AT&T Advisory #64 (3.8) 0 dBm0 Input Signal
DP$_R$	Receive Single Frequency Distortion Products (2916)			$-$46	dBm0	AT&T Advisory #64 (3.8) 0 dBm0 Input Signal
IMD$_1$	Intermodulation Distortion, End to End Measurement			$-$35	dB	CCITT G.712 (7.1)
IMD$_2$	Intermodulation Distortion, End to End Measurement			$-$49	dBm0	CCITT G.712 (7.2)
SOS	Spurious Out of Band Signals, End to End Measurement			$-$25	dBm0	CCITT G.712 (6.1)
SIS	Spurious In Band Signals, End to End Measurement			$-$40	dBm0	CCITT G.712 (9)
D$_{AX}$	Transmit Absolute Delay		245		μs	Fixed Data Rate. CLK$_X$ = 2.048 MHz; 0 dBm0, 1.02 KHz Input Signal, Unity Gain. Measure at D$_X$.
D$_{DX}$	Transmit Differential Envelope Delay Relative to D$_{AX}$		170 95 45 105		μs μs μs μs	f = 500 Hz to 600 Hz f = 600 Hz to 1000 Hz f = 1000 Hz to 2600 Hz f = 2600 Hz to 2800 Hz
D$_{AR}$	Receive Absolute Delay		190		μs	Fixed Data Rate, CLK = 2.048 MHz; Digital Input is DMW Codes. Measure at PWRO+
D$_{DR}$	Receive Differential Envelope Delay Relative to D$_{AR}$		45 35 85 110		μs μs μs μs	f = 500 Hz to 600 Hz f = 600 Hz to 1000 Hz f = 1000 Hz to 2600 Hz f = 2600 Hz to 2800 Hz

TRANSMIT CHANNEL TRANSFER CHARACTERISTICS
Input amplifier is set for unity gain, inverting.

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
G_{RX}	Gain Relative to Gain at 1.02 KHz					0 dBm0 Signal Input at VF_XI-
	16.67 Hz			−30	dB	
	50 Hz			−25	dB	
	60 Hz			−23	dB	
	200 Hz	−1.8		−0.125	dB	
	300 to 3000 Hz	−0.125		+0.125	dB	
	3300 Hz	−0.35		+0.03	dB	
	3400 Hz	−0.7		−0.10	dB	
	4000 Hz			−14	dB	
	4600 Hz and Above			−32	dB	

5
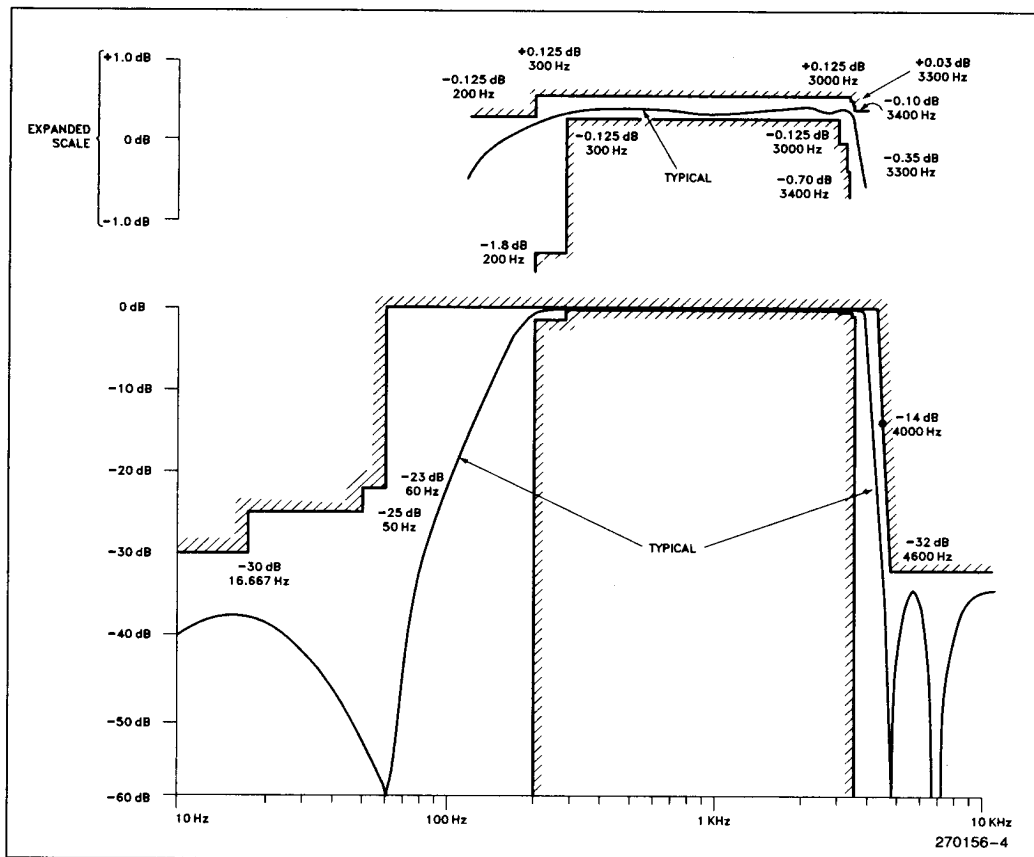
Figure 4. Transmit Channel

270156-4

RECEIVE CHANNEL TRANSFER CHARACTERISTICS

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
G_{RR}	Gain Relative to Gain at 1.02 KHz					0 dBm0 Signal Input at D_R
	Below 200 Hz			+0.125	dB	
	200 Hz	−0.5		+0.125	dB	
	300 to 3000 Hz	+0.125		+0.125	dB	
	3300 Hz	−0.35		+0.03	dB	
	3400 Hz	−0.7		−0.1	dB	
	4000 Hz			−14	dB	
	4600 Hz and Above			−30	dB	
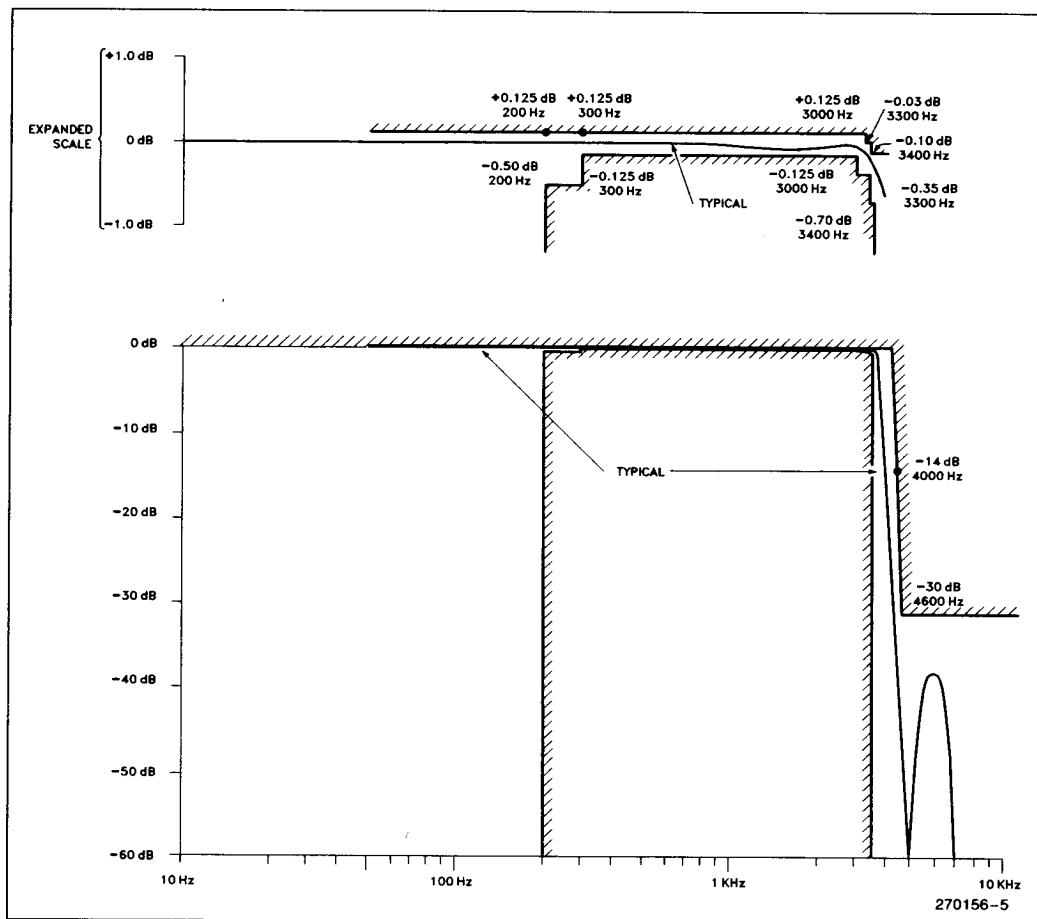
Figure 5. Receive Channel

270156–5

A.C. CHARACTERISTICS—TIMING PARAMETERS

CLOCK SECTION

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
t_{CY}	Clock Period, CLK	488			ns	$f_{CLK} = 2.048$ MHz
t_{CLK}	Clock Pulse Width, CLK	220			ns	
t_{DCLK}	Data Clock Pulse Width	220			ns	64 KHz $\leq f_{DCLK} \leq 2.048$ MHz
t_{CDC}	Clock Duty Cycle, CLK	45	50	55	%	
t_r, t_f	Clock Rise and Fall Time	5		30	ns	

TRANSMIT SECTION, FIXED DATA RATE MODE[1]

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
t_{DZX}	Data Enabled on TS Entry	0		145	ns	$0 < C_{LOAD} < 100$ pF
t_{DDX}	Data Delay from CLK	0		145	ns	$0 < C_{LOAD} < 100$ pF
t_{HZX}	Data Float on TS Exit	60		215	ns	$C_{LOAD} = 0$
t_{SON}	Timeslot X to Enable	0		145	ns	$0 < C_{LOAD} < 100$ pF
t_{SOFF}	Timeslot X to Disable	60		215	ns	$C_{LOAD} = 0$
t_{FSD}	Frame Sync Delay	100		t_{CLK}	ns	

RECEIVE SECTION, FIXED DATA RATE MODE

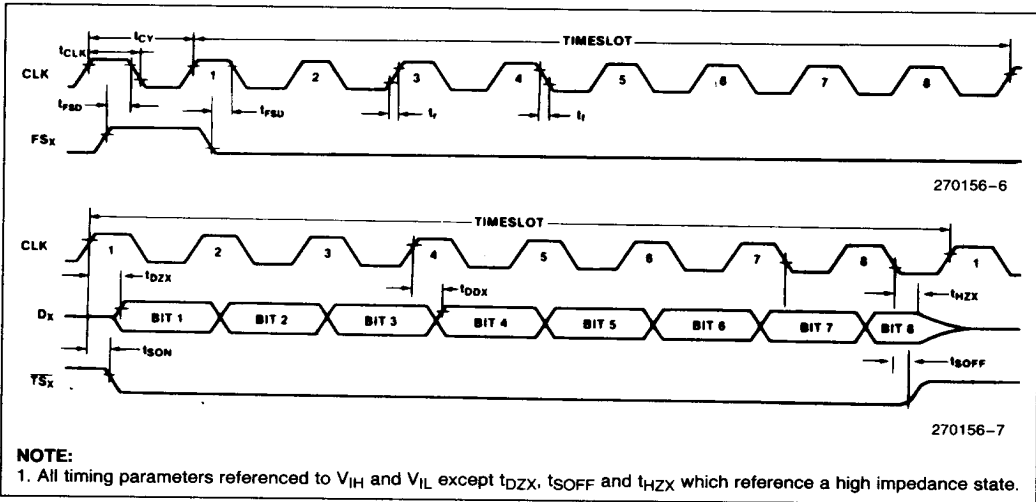| Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
t_{DSR}	Receive Data Setup	10			ns	
t_{DHR}	Receive Data Hold	60			ns	
t_{FSD}	Frame Sync Delay	100		t_{CLK}	ns	

NOTE:
1. Timing parameters T_{DZX}, T_{HZX}, and T_{SOFF} are referenced to a high impedance state.

5

WAVEFORMS

Fixed Data Rate Timing

TRANSMIT TIMING

270156-6

270156-7

NOTE:
1. All timing parameters referenced to V_{IH} and V_{IL} except t_{DZX}, t_{SOFF} and t_{HZX} which reference a high impedance state.

RECEIVE TIMING

270156-8

270156-9

NOTE:
1. All timing parameters referenced to V_{IH} and V_{IL}.
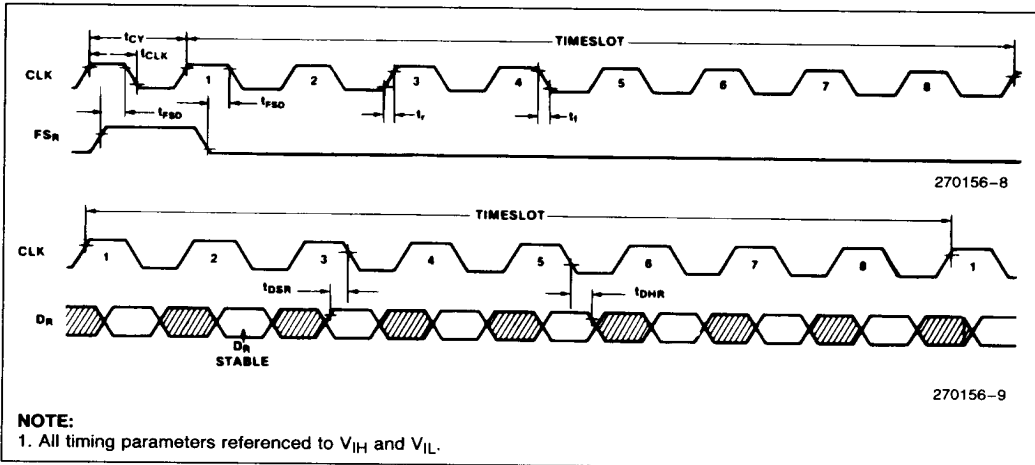
TRANSMIT SECTION, VARIABLE DATA RATE MODE[1]

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
t_{TSDX}	Timeslot Delay from $DCLK_X$[2]	140		$t_{DX} - 140$	ns	
t_{FSD}	Frame Sync Delay	100		$t_{CY} - 100$	ns	
t_{DDX}	Data Delay from $DCLK_X$	0		100	ns	$0 < C_{LOAD} < 100$ pF
t_{DON}	Timeslot to D_X Active	0		50	ns	$0 < C_{LOAD} < 100$ pF
t_{DOFF}	Timeslot to D_X Inactive	0		80	ns	$0 < C_{LOAD} < 100$ pF
t_{DX}	Data Clock Period	488		15620	ns	
t_{DFSX}	Data Delay from FS_X	0		140	ns	

RECEIVE SECTION, VARIABLE DATA RATE MODE

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
t_{TSDR}	Timeslot Delay from $DCLK_R$[3]	140		$t_{DR} - 140$	ns	
t_{FSD}	Frame Sync Delay	100		$t_{CY} - 100$	ns	
t_{DSR}	Data Setup Time	10			ns	
t_{DHR}	Data Hold Time	60			ns	
t_{DR}	Data Clock Period	488		15620	ns	
t_{SER}	Timeslot End Receive Time	60			ns	

64 KB OPERATION, VARIABLE DATA RATE MODE

| Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
t_{FSLX}	Transmit Frame Sync Minimum Downtime	488			ns	FS_X is TTL High for Remainder of Frame
t_{FSLR}	Receive Frame Sync Minimum Downtime	1952			ns	FS_R is TTL High for Remainder of Frame
t_{DCLK}	Data Clock Pulse Width			10	μs	

NOTES:
1. Timing parameters t_{DON} and t_{DOFF} are referenced to a high impedance state.
2. t_{FSLX} minimum requirements overrides t_{TSDX} maximum spec for 64 KHz operation.
3. t_{FSLR} minimum requirements overrides t_{TSDR} maximum spec for 64 KHz operation.

5

VARIABLE DATA RATE TIMING

TRANSMIT TIMING

270156–10

RECEIVE TIMING

270156–11
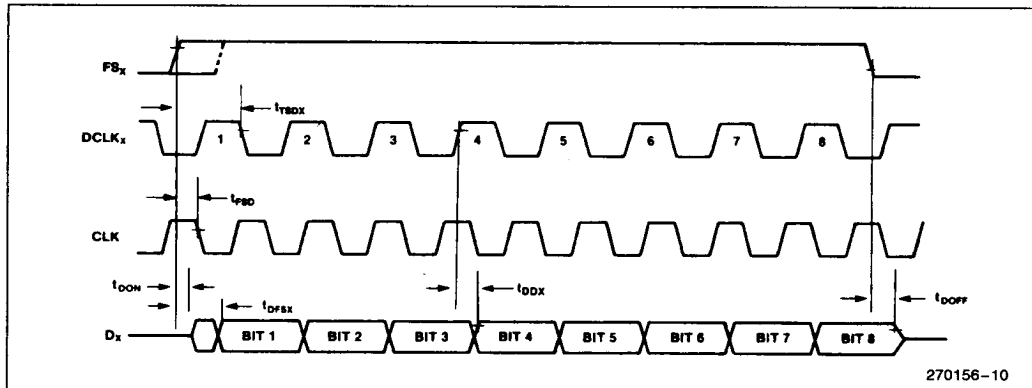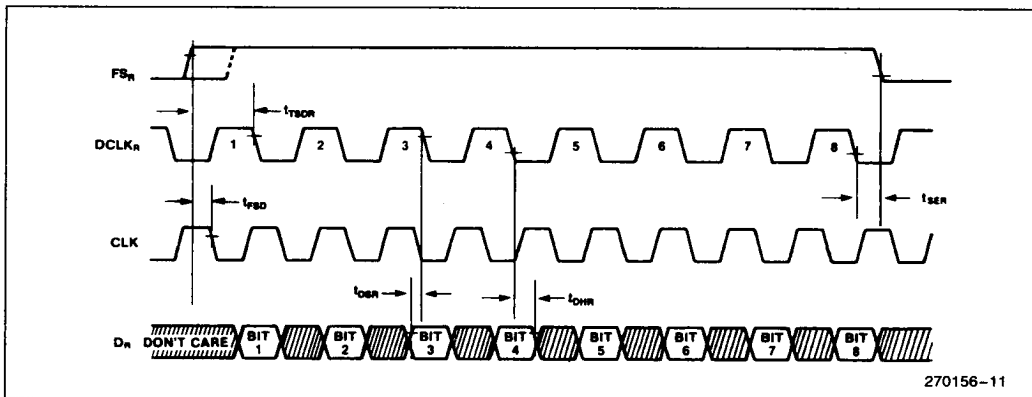
NOTE:
1. All timing parameters referenced to V_{IH} and V_{IL} except t_{DON} and t_{OFF} which reference a high impedance state.

A.C. TESTING INPUT, OUTPUT WAVEFORM

INPUT/OUTPUT

270156–12

A.C. Testing: Inputs are driven at 2.4V for a Logic "1" and 0.45V for a Logic "0". Timing measurements are made at 2.0V for a Logic "1" and 0.8V for a Logic "0".